



SOT1312-1

HXSON4: plastic thermal enhanced extremely thin small outline package; no leads; 4 terminals; body 2.0 mm x 1.5 mm x 0.5 mm

11 July 2017

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HXSON4
Package type industry code	HXSON4
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	5-11-2012
Manufacturer package code	SOT1312

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.4	-	1.5	1.6	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	4	-	



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2. Package outline

HXSON4: plastic thermal enhanced extremely thin small outline package; no leads; 4 terminals; body 2.0 x 1.5 x 0.5 mm

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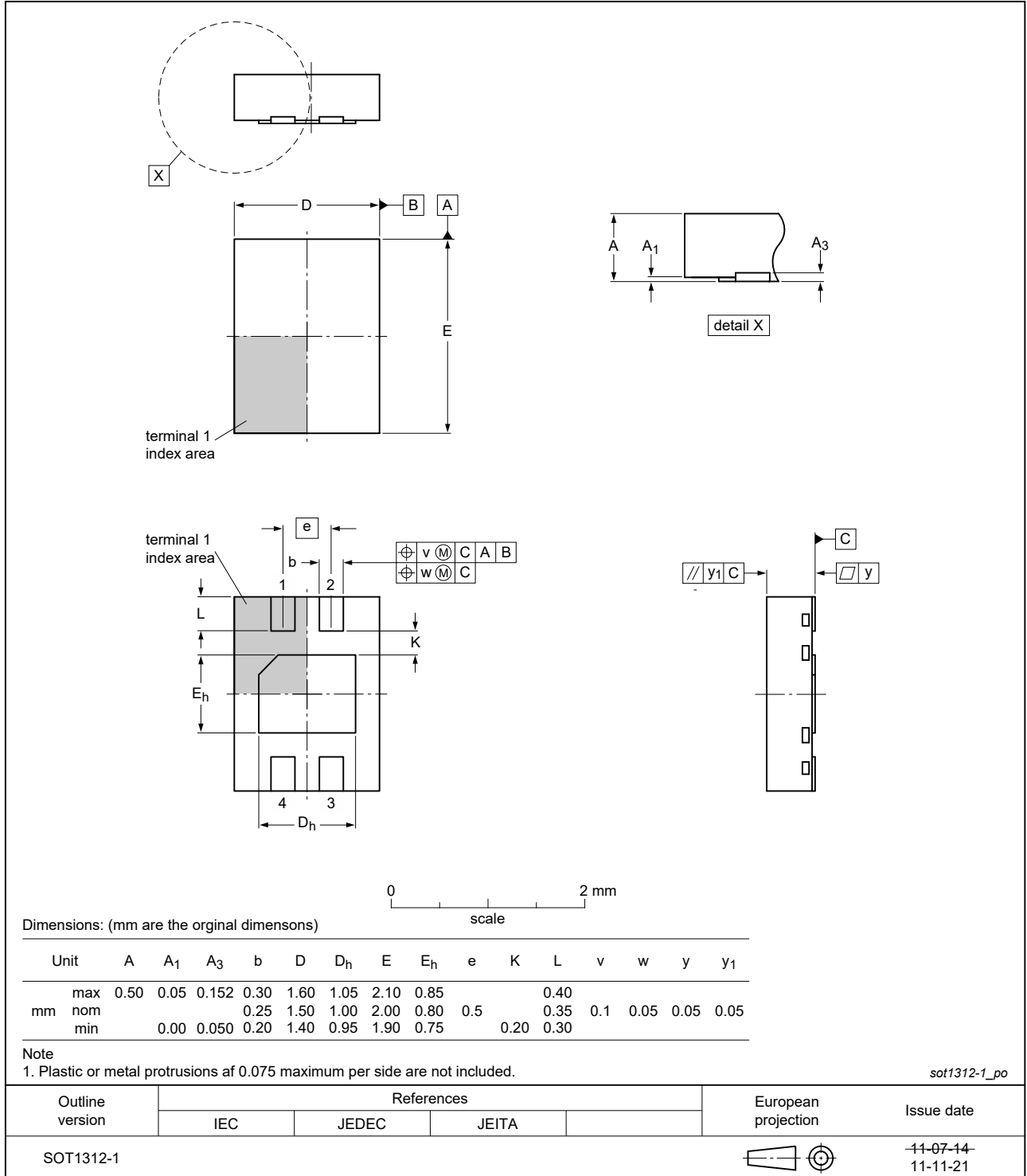


Fig. 1. Package outline HXSON4 (SOT1312-1)

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4. Legal information

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